

## Electronic Patent Application Fee Transmittal

<b>Electronic Patent Application Fee Transmittal</b>				
<b>Application Number:</b>	10521176			
<b>Filing Date:</b>	14-Jan-2005			
<b>Title of Invention:</b>	Solid support having electrostatic layer and use thereof			
<b>First Named Inventor/Applicant Name:</b>	Hiroshi Okamura			
<b>Filer:</b>	Roger Lowen Browdy/Sharnita Davenport			
<b>Attorney Docket Number:</b>	OKAMURA6			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Post-Allowance-and-Post-Issuance:				
Statutory disclaimer	1814	1	130	130
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>130</b>